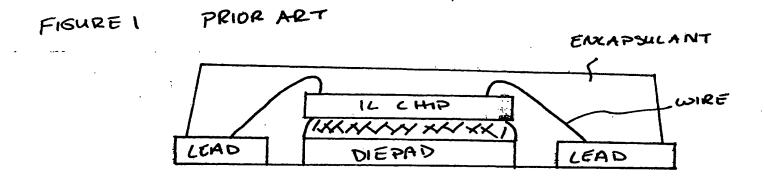
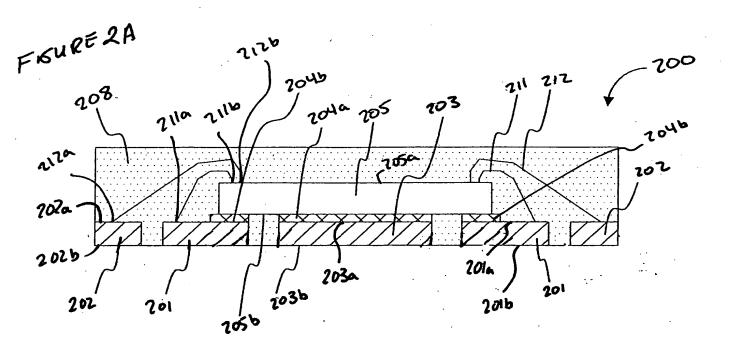
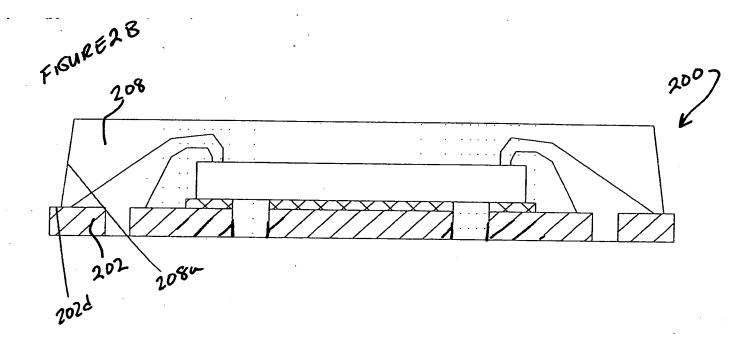
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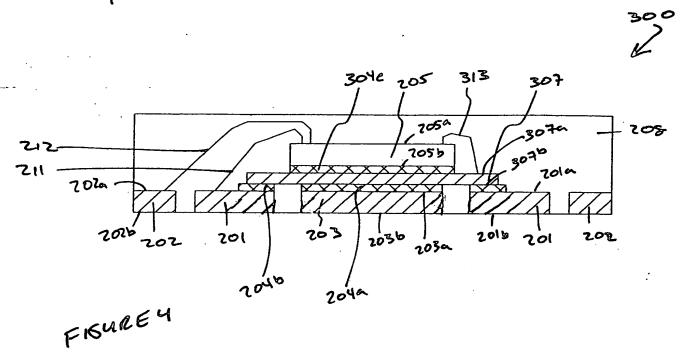


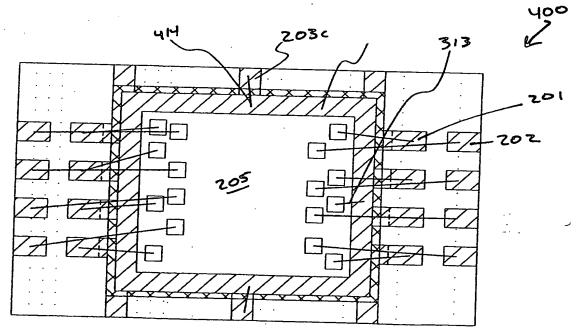
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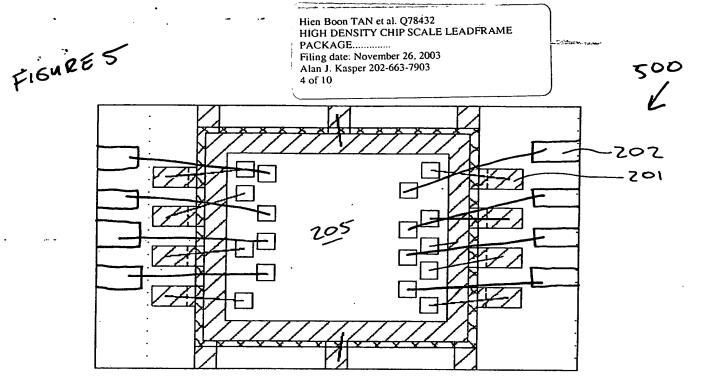


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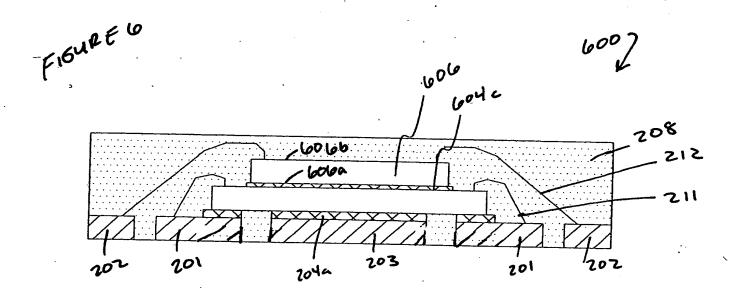
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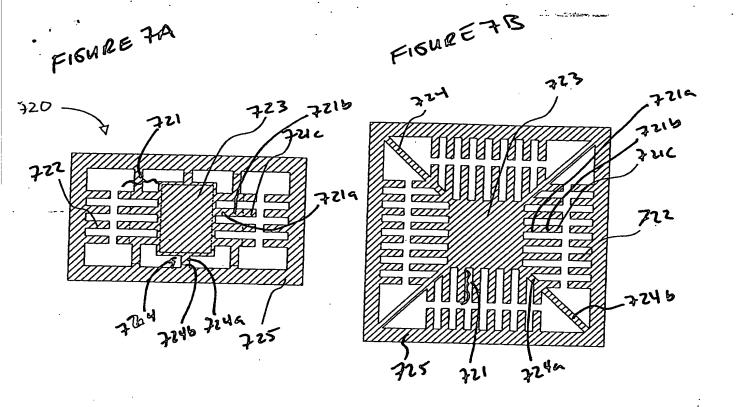


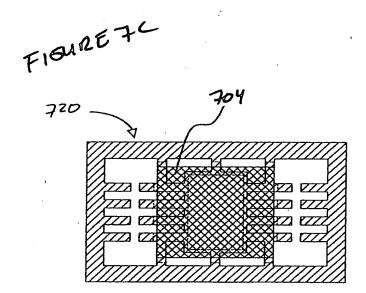


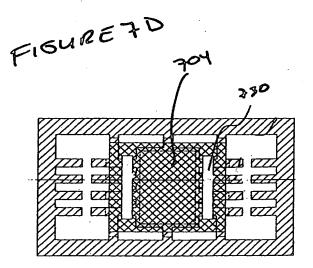


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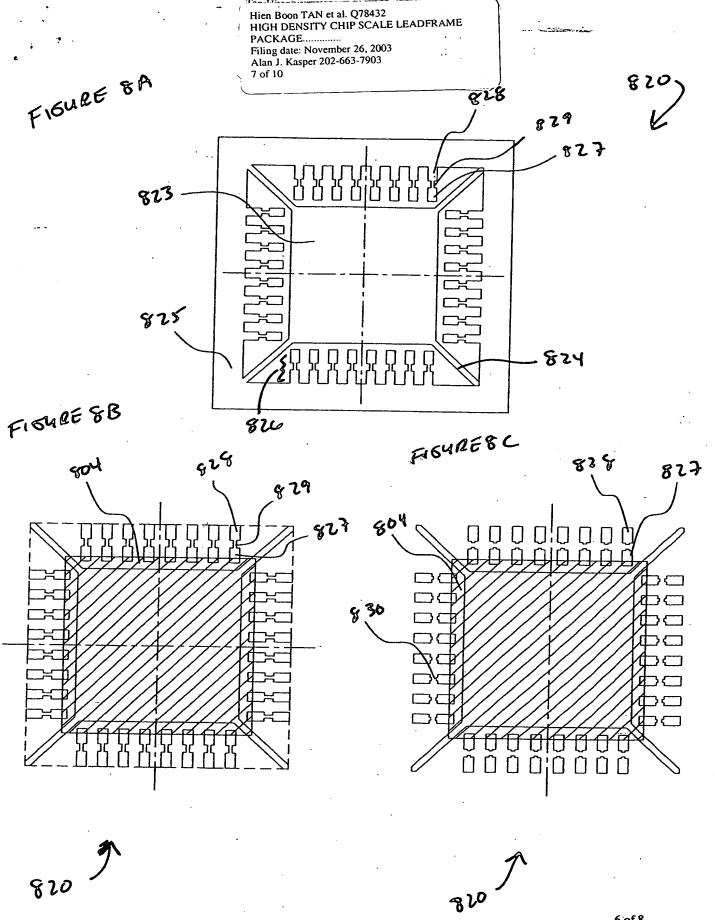






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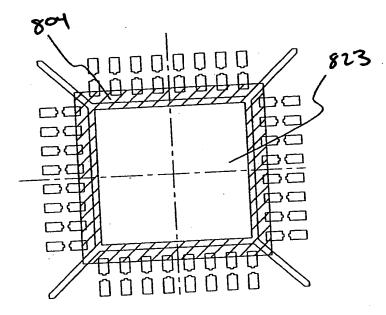


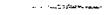
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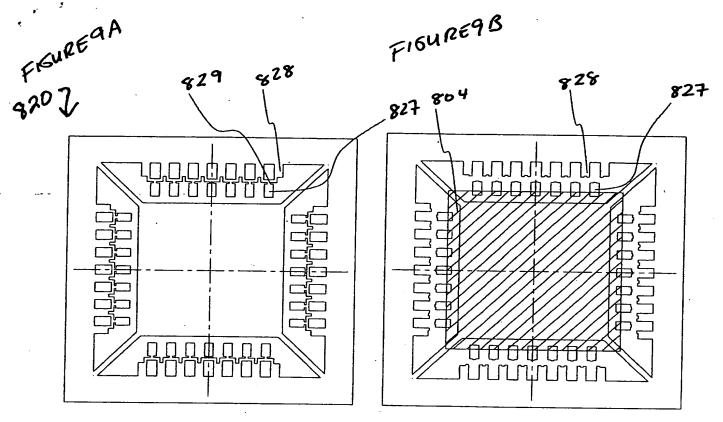
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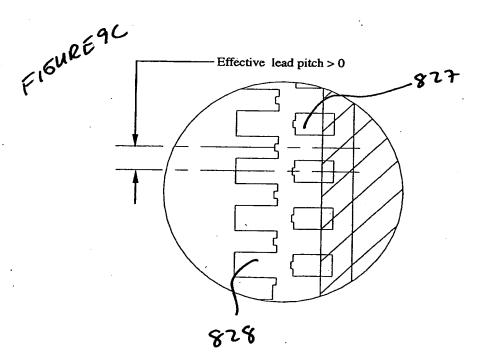
FIGURE 8D











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